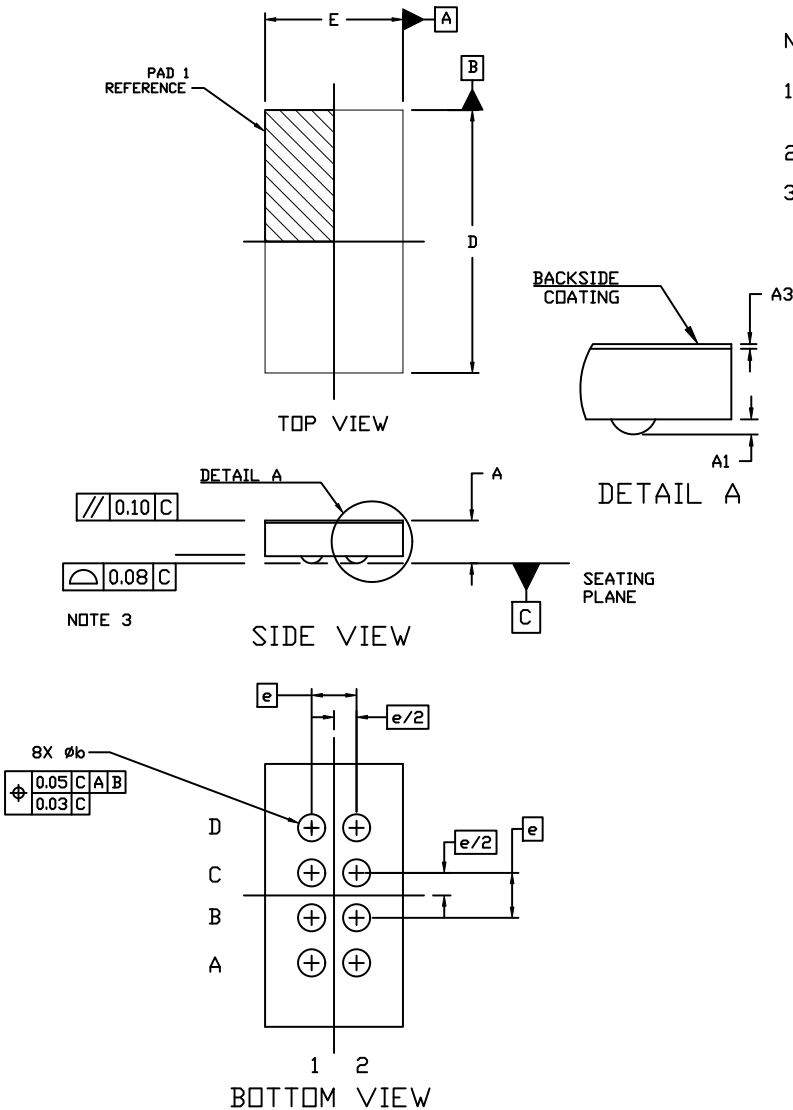


**WLCSP8 2.92x1.53x0.525**  
CASE 567YR  
ISSUE O

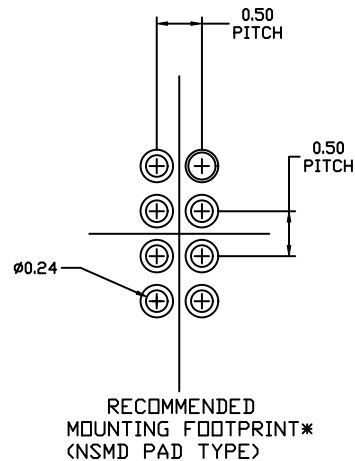
DATE 21 NOV 2019



NOTES:

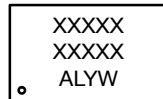
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.525
A1	0.03	0.08	0.13
A3	0.025 REF		
b	0.25	0.30	0.35
D	2.82	2.92	3.02
E	1.43	1.53	1.63
e	0.50 BSC		



\* For additional information on our Pb-Free strategy and soldering details, please download the [DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D](#).

**GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

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